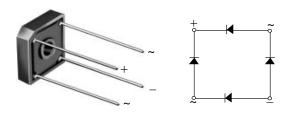


Vishay General Semiconductor

# **Glass Passivated Single-Phase Bridge Rectifier**



Case Style GBPC6

MAJOR RATINGS AND CHARACTERISTICS							
I <sub>F(AV)</sub>	6 A						
V <sub>RRM</sub>	50 V to 1000 V						
I <sub>FSM</sub>	175 A						
I <sub>R</sub>	5 μΑ						
V <sub>F</sub>	1.0 V						
T <sub>j</sub> max.	150 °C						

#### **FEATURES**





- · Ideal for printed circuit boards
- Typical I<sub>R</sub> less than 0.5 μA
- · High surge current capability
- High case dielectric strength 1500 V<sub>RMS</sub>
- Solder Dip 260 °C, 40 seconds
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

### **TYPICAL APPLICATIONS**

General purpose use in ac-to-dc bridge full wave rectification for Power Supply, Home Appliances, Office Equipment, Industrial Automation applications.

#### **MECHANICAL DATA**

Case: GBPC6

Epoxy meets UL 94V-0 flammability rating

Terminals: Silver plated leads, solderable per

J-STD-002B and JESD22-B102D E4 suffix for commercial grade

**Polarity:** As marked, positive lead by belevled corner **Mounting Torque:** 10 cm-kg (8.8 inches-lbs) max. **Recommended Torque:** 5.7 cm-kg (5 inches-lbs)

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)									
PARAMETER	SYMBOL	GBPC 6005	GBPC 601	GBPC 602	GBPC 604	GBPC 606	GBPC 608	GBPC 610	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	٧
Maximum RMS bridge input voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	٧
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	٧
$ \begin{array}{ccc} \text{Maximum average forward} & & T_{\text{C}} = 50  ^{\circ}\text{C}  ^{(1,2)} \\ \text{rectified output current at} & & T_{\text{A}} = 40  ^{\circ}\text{C}  ^{(3)} \\ \end{array} $	I <sub>F(AV)</sub>	6.0 3.0					Α		
Peak forward surge current single sine-wave superimposed on rated load	I <sub>FSM</sub>	175				Α			
Rating for fusing (t < 8.3 ms)	I <sup>2</sup> t	127			A <sup>2</sup> sec				
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	TG - 55 to + 150				°C			

#### Note:

- (1) Bolt down on heat-sink with silicone thermal compound between bridge and mounting surface for maximum heat transfer with #6 screw
- (2) Unit mounted on 5.5 x 6.0 x 0.11" thick (14 x 15 x 0.3 cm) Al. Plate
- (3) Unit mounted on P.C.B. at 0.375" (9.5 mm) lead length with 0.5 x 0.5" (12 x 12 mm) copper pads

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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)										
PARAMETER	TEST CONDITIONS	SYMBOL	GBPC 6005	GBPC 601	GBPC 602	GBPC 604	GBPC 606	GBPC 608	GBPC 610	UNIT
Maximum instantaneous forward voltage drop per diode	at 3.0 A	V <sub>F</sub>	1.0						٧	
Maximum DC reverse current at rated DC blocking voltage per diode	T <sub>A</sub> = 25 °C T <sub>A</sub> = 125 °C	I <sub>R</sub>	5.0 500					μΑ		
Typical junction capacitance per diode	at 4.0 V, 1 MHz	CJ	186 90					pF		

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)								
PARAMETER SYMBOL GBPC 6005 GBPC 601 GBPC 602 GBPC 604 GBPC 608 GBPC 610						UNIT		
Typical thermal resistance <sup>(1)</sup>	$egin{array}{c} {\sf R}_{ heta {\sf JA}} \ {\sf R}_{ heta {\sf JC}} \end{array}$	22 7.3					°C/W	

#### Note:

- (1) Bolt down on heat-sink with silicone thermal compound between bridge and mounting surface for maximum heat transfer with #6 screw
- (2) Unit mounted on 5.5 x 6.0 x 0.11" thick (14 x 15 x 0.3 cm) Al. Plate
- (3) Unit mounted on P.C.B. at 0.375" (9.5 mm) lead length with 0.5 x 0.5" (12 x 12 mm) copper pads

ORDERING INFORMATION								
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE				
GBPC606-E4/51	3.2	51	100	Paper Box				

### **RATINGS AND CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25 °C unless otherwise noted)

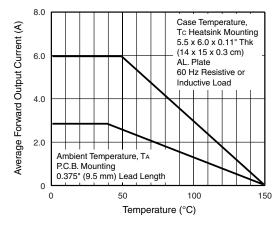


Figure 1. Derating Curve Output Rectified Current

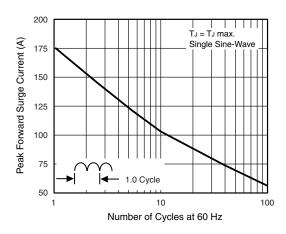


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current Per Diode

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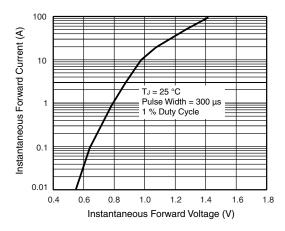


Figure 3. Typical Forward Characteristics Per Diode

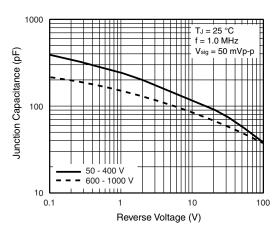


Figure 5. Typical Junction Capacitance Per Diode

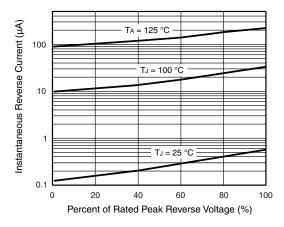


Figure 4. Typical Reverse Leakage Characteristics Per Diode

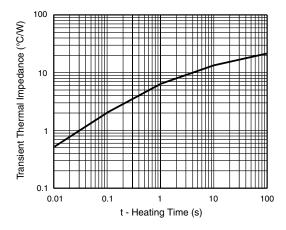
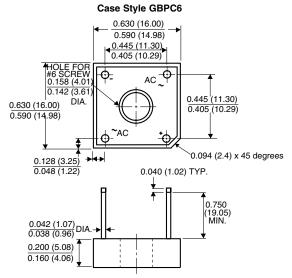


Figure 6. Typical Transient Thermal Impedance Per Diode

### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)



Polarity shown on side of case: Positive lead by beveled corner

## **Legal Disclaimer Notice**



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